

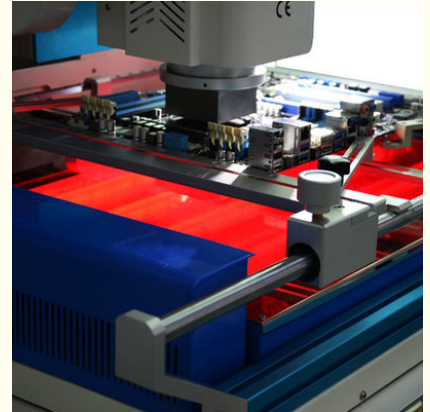


WDS 800 BGA Optical Alignment System Chip Welding and Disassembly

Our Product Introduction

Basic Information

- Place of Origin: China
- Brand Name: WDS
- Certification: CE
- Model Number: WDS-800
- Minimum Order Quantity: 1 UNIT
- Packaging Details: Wooden case
- Delivery Time: 8-15 working days
- Payment Terms: T/T, Western Union, MoneyGram
- Supply Ability: 150 UNITS PER MONTH



Product Specification

- Max PCB Size: W650*D610mm
- BGA Size: 1*1-80*80mm
- Bottom Pre-heating: IR 5000W
- Upper Heating Power: Hot Air 1200W
- Lower Heating Power: Hot Air 1200W
- Highlight: **Chip Disassembly BGA Optical Alignment System**
, Chip Welding BGA Optical Alignment System,
Chip Disassembly Automatic BGA Reballing Machine

Product Description

WDS-800 Optical Alignment Automatic BGA Rework Station

Specification

Max PCB Size	W650*D610mm
PCB Thickness	0.5-8mm
BGA Size	1*1-80*80mm
Min.ball pitch	0.15mm
Max Weight of BGA	150g
Placement precision	±0.01mm
PCB Locating Way	Outer or location hole
Temperature Control	K-type thermocouple,close loop control
Lower Heating Power	Hot air 1200W
Upper Heating Power	Hot air 1200W
Bottom pre-heating	IR5000W
Power Supply	(Double Phase)220V,50/60Hz
Machine Dimension	L700*W1000*H950mm(without frame)
Machine Weight	140kg

Outstanding performance features

Multi-language menu interface

Automatic feeding device

X/Y axis can be controlled by joystick, easy and fast operation

Imported high-definition CCD(2 million pixels) optical alignment system

High precision temperature control system, accurate temperature control

HD optical alignment and interlligent control

The integrated design of hot air head and mounting head has the functions of automatic mounting, automatic welding and automatic disassembly. High precision K-type thermocouple(KSENSOR) Closed Loop control, up and down independent temperature measurement, temperature control accuracy up to ± 1 degree, Over-temperature protection alarm function, software encryption and anti-stay function.

The X/Y/Z axis is automatically shifted

The upper temperature zone is controlled by the joystick servosystem, X and Y are automatically controlled by the motor movement mode, so that the alignment is fast and convenient, and the speed can be controlled.

Vacuum adsrption and preheating platform

The upper heating head is equipped with a vacuum suction pipe for chip adsorption. The bottom preheating platform adopts imported excellent heating materials(infrared gold-plated light tube)+anti-flash thermostatic glass(temperature resistance up to 1800°C). The preheating area is up to 500*420mm. The preheating platform, splint device and cooling system can be moved as a whole in the X direction. Make PCB positioning and folding welding more safe and convenient.



Shenzhen Wisdomshow Technology Co.,Ltd



+86 17727914291



Mia@wdsbga.cn



bgaxraymachine.com

No.6,Haosi Western Industry,Shangjing Town,Bao'an District,Shenzhen,China